

ABSTRACT

A low-CTE packaging material for assembling a semiconductor die into a package and a method for assembling a semiconductor die into a package, in which the packaging material comprises a negative-CTE material. The low-CTE packaging material in accordance with the embodiments of the invention may be a die attach material, a lid attach material, or an encapsulant, such as a mold compound or glob-top material. Preferably, the negative-CTE material is a tungstate compound, such as zirconium tungstate, hafnium tungstate or a solution of zirconium and hafnium tungstate.